

# 74ALVCHS162830A 1-BIT TO 2-BIT ADDRESS DRIVER WITH 3-STATE OUTPUTS

SCES624 – FEBRUARY 2005

- Member of the Texas Instruments Widebus™ Family
- Output Ports Have Series Damping Resistors, So No External Resistors Are Required
- Diodes on Inputs Clamp Overshoot
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)

## description/ordering information

This 1-bit to 2-bit address driver is designed for 2.3-V to 3.6-V  $V_{CC}$  operation.

Diodes to  $V_{CC}$  have been added on the inputs to clamp overshoot.

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

The outputs, which are designed to sink up to 12 mA, include series damping resistors to reduce overshoot and undershoot.

The ALVCHS162830A is an improved version of the LVCHS162830 (non-A version) and has been optimized for lower power consumption and higher AC drive. Higher AC drive provides capability to drive loads with a faster edge rate.

To ensure the high-impedance state during power up or power down, the output-enable ( $\overline{OE}$ ) input should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

DBB PACKAGE  
(TOP VIEW)

2Y2	1	80	1Y3
1Y2	2	79	2Y3
GND	3	78	GND
2Y1	4	77	1Y4
1Y1	5	76	2Y4
$V_{CC}$	6	75	$V_{CC}$
A1	7	74	1Y5
A2	8	73	2Y5
GND	9	72	GND
A3	10	71	1Y6
A4	11	70	2Y6
GND	12	69	GND
A5	13	68	1Y7
A6	14	67	2Y7
$V_{CC}$	15	66	$V_{CC}$
A7	16	65	1Y8
A8	17	64	2Y8
GND	18	63	GND
A9	19	62	1Y9
$\overline{OE1}$	20	61	2Y9
$\overline{OE2}$	21	60	1Y10
A10	22	59	2Y10
GND	23	58	GND
A11	24	57	1Y11
A12	25	56	2Y11
$V_{CC}$	26	55	$V_{CC}$
A13	27	54	1Y12
A14	28	53	2Y12
GND	29	52	GND
A15	30	51	1Y13
A16	31	50	2Y13
GND	32	49	GND
A17	33	48	1Y14
A18	34	47	2Y14
$V_{CC}$	35	46	$V_{CC}$
2Y18	36	45	1Y15
1Y18	37	44	2Y15
GND	38	43	GND
2Y17	39	42	1Y16
1Y17	40	41	2Y16



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Widebus is a trademark of Texas Instruments.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

Copyright © 2005, Texas Instruments Incorporated

# 74ALVCHS162830A

## 1-BIT TO 2-BIT ADDRESS DRIVER

### WITH 3-STATE OUTPUTS

SCES624 – FEBRUARY 2005

#### description/ordering information

#### ORDERING INFORMATION

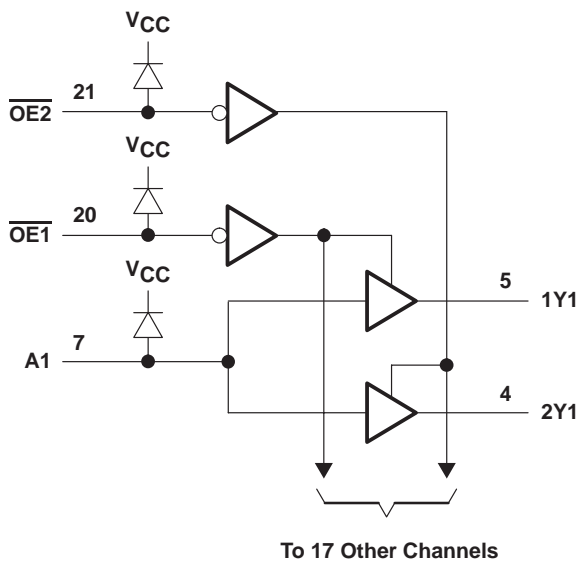
TA	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	TVSOP – DBB	Tape and reel	74ALVCHS162830AGR	ALVCHS162830A

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).

#### FUNCTION TABLE

INPUTS			OUTPUTS	
$\overline{OE1}$	$\overline{OE2}$	A	1Yn	2Yn
L	H	H	H	Z
L	H	L	L	Z
H	L	H	Z	H
H	L	L	Z	L
L	L	H	H	H
L	L	L	L	L
H	H	X	Z	Z

#### logic diagram (positive logic)



# 74ALVCHS162830A 1-BIT TO 2-BIT ADDRESS DRIVER WITH 3-STATE OUTPUTS

SCES624 – FEBRUARY 2005

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, $V_{CC}$ .....	–0.5 V to 4.6 V
Input voltage range, $V_I$ (see Note 1) .....	–0.5 V to $V_{CC} + 0.5$ V
Output voltage range, $V_O$ (see Notes 1 and 2) .....	–0.5 V to $V_{CC} + 0.5$ V
Input clamp current, $I_{IK}$ ( $V_I < 0$ , $V_I > V_{CC}$ ) .....	±50 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ ) .....	–50 mA
Continuous output current, $I_O$ .....	±50 mA
Continuous current through each $V_{CC}$ or GND .....	±100 mA
Package thermal impedance, $\theta_{JA}$ (see Note 3) .....	64°C/W
Storage temperature range, $T_{stg}$ .....	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.  
 2. This value is limited to 4.6 V maximum.  
 3. The package thermal impedance is calculated in accordance with JESD 51-7.

## recommended operating conditions (see Note 4)

		MIN	MAX	UNIT
$V_{CC}$	Supply voltage	2.3	3.6	V
$V_{IH}$	High-level input voltage	$V_{CC} = 2.3$ V to 2.7 V	1.7	V
		$V_{CC} = 2.7$ V to 3.6 V	2	
$V_{IL}$	Low-level input voltage	$V_{CC} = 2.3$ V to 2.7 V	0.7	V
		$V_{CC} = 2.7$ V to 3.6 V	0.8	
$V_I$	Input voltage	0	$V_{CC}$	V
$V_O$	Output voltage	0	$V_{CC}$	V
$I_{OH}$	High-level output current	$V_{CC} = 2.3$ V	–6	mA
		$V_{CC} = 2.7$ V	–8	
		$V_{CC} = 3$ V	–12	
$I_{OL}$	Low-level output current	$V_{CC} = 2.3$ V	6	mA
		$V_{CC} = 2.7$ V	8	
		$V_{CC} = 3$ V	12	
$\Delta t/\Delta v$	Input transition rise or fall rate		10	ns/V
$T_A$	Operating free-air temperature	–40	85	°C

NOTE 4: All unused control inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



# 74ALVCHS162830A

## 1-BIT TO 2-BIT ADDRESS DRIVER WITH 3-STATE OUTPUTS

SCES624 – FEBRUARY 2005

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	MIN	TYP†	MAX	UNIT	
V <sub>IK</sub>	I <sub>I</sub> = -18 mA	2.3 V			-1.2	V	
	I <sub>I</sub> = 18 mA	2.3 V			V <sub>CC</sub> + 1.2		
V <sub>OH</sub>	I <sub>OH</sub> = -100 μA	2.3 V to 3.6 V			V <sub>CC</sub> - 0.2	V	
	I <sub>OH</sub> = -4 mA, V <sub>IH</sub> = 1.7 V	2.3 V			1.9		
	I <sub>OH</sub> = -6 mA	V <sub>IH</sub> = 1.7 V	2.3 V				1.7
		V <sub>IH</sub> = 2 V	3 V				2.4
	I <sub>OH</sub> = -8 mA, V <sub>IH</sub> = 2 V	2.7 V			2		
I <sub>OH</sub> = -12 mA, V <sub>IH</sub> = 2 V	3 V			2			
V <sub>OL</sub>	I <sub>OL</sub> = 100 μA	2.3 V to 3.6 V			0.2	V	
	I <sub>OL</sub> = 4 mA	V <sub>IL</sub> = 0.7 V	2.3 V				0.4
		V <sub>IL</sub> = 0.7 V	2.3 V				0.55
	I <sub>OL</sub> = 6 mA	V <sub>IL</sub> = 0.8 V	3 V				0.55
		V <sub>IL</sub> = 0.8 V	2.7 V				0.6
	I <sub>OL</sub> = 12 mA, V <sub>IL</sub> = 0.8 V	3 V			0.8		
I <sub>I</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	3.6 V			±5	μA	
I <sub>I(hold)</sub>	V <sub>I</sub> = 0.7 V	2.3 V			45	μA	
	V <sub>I</sub> = 1.7 V	2.3 V			-45		
	V <sub>I</sub> = 0.8 V	3 V			75		
	V <sub>I</sub> = 2 V	3 V			-75		
	V <sub>I</sub> = 0 to 3.6 V‡	3.6 V			±500		
I <sub>OZ</sub>	V <sub>O</sub> = V <sub>CC</sub> or GND	3.6 V			±10	μA	
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0	3.6 V			20	μA	
ΔI <sub>CC</sub>	One input at V <sub>CC</sub> - 0.6 V, Other inputs at V <sub>CC</sub> or GND	3 V to 3.6 V			500	μA	
C <sub>i</sub>	Control inputs	V <sub>I</sub> = V <sub>CC</sub> or GND	3.3 V			3.5	pF
	Data inputs					4.5	
C <sub>o</sub>	Outputs	V <sub>O</sub> = V <sub>CC</sub> or GND	3.3 V			4.5	pF

† All typical values are at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C.

‡ This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

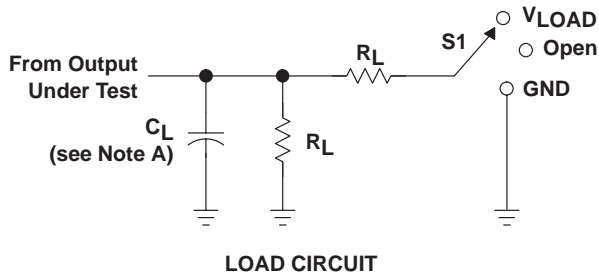
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 2.5 V ± 0.2 V		V <sub>CC</sub> = 2.7 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t <sub>pd</sub>	A	Y	1.2	3.8	4		1.7	3.5	ns
t <sub>en</sub>	$\overline{\text{OE}}$	Y	1	5.7	5.7		1	4.8	ns
t <sub>dis</sub>	$\overline{\text{OE}}$	Y	1	4.9	5.4		1.7	5.2	ns

operating characteristics, T<sub>A</sub> = 25°C

PARAMETER		TEST CONDITIONS	V <sub>CC</sub> = 2.5 V		V <sub>CC</sub> = 3.3 V		UNIT
			TYP	TYP	TYP	TYP	
C <sub>pd</sub>	Power dissipation capacitance per bit (one output switching)	One $\overline{\text{OE}}$ enabled	C <sub>L</sub> = 0, f = 10 MHz	17	17.5	pF	
		All outputs disabled		0.4	0.5		

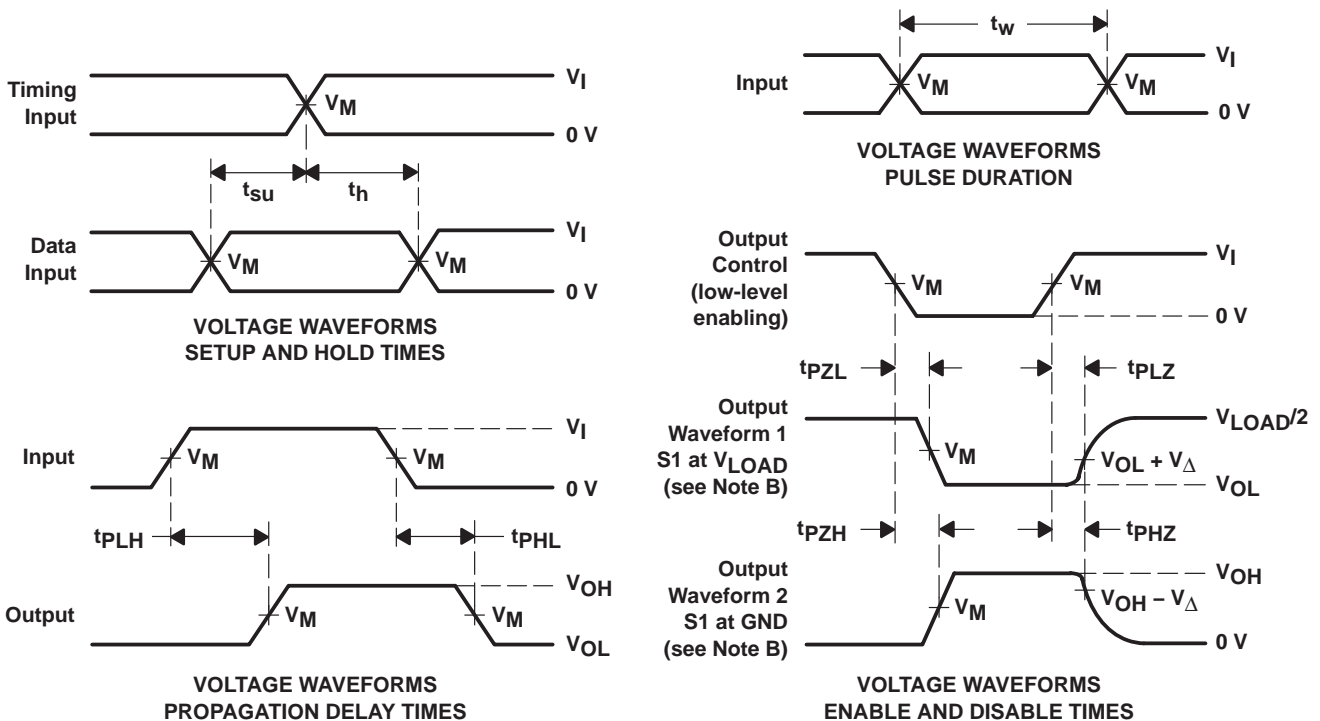


**PARAMETER MEASUREMENT INFORMATION**



TEST	S1
$t_{pd}$ $t_{PLZ}/t_{PZL}$ $t_{PHZ}/t_{PZH}$	Open $V_{LOAD}$ GND

$V_{CC}$	INPUT		$V_M$	$V_{LOAD}$	$C_L$	$R_L$	$V_{\Delta}$
	$V_I$	$t_r/t_f$					
$2.5\text{ V} \pm 0.2\text{ V}$	$V_{CC}$	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	500 $\Omega$	0.15 V
2.7 V	2.7 V	$\leq 2.5\text{ ns}$	1.5 V	6 V	50 pF	500 $\Omega$	0.3 V
$3.3\text{ V} \pm 0.3\text{ V}$	2.7 V	$\leq 2.5\text{ ns}$	1.5 V	6 V	50 pF	500 $\Omega$	0.3 V



- NOTES:
- $C_L$  includes probe and jig capacitance.
  - Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
  - All input pulses are supplied by generators having the following characteristics: PRR  $\leq 10\text{ MHz}$ ,  $Z_O = 50\ \Omega$ .
  - The outputs are measured one at a time, with one transition per measurement.
  - $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
  - $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
  - $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
  - All parameters and waveforms are not applicable to all devices.

**Figure 1. Load Circuit and Voltage Waveforms**

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
74ALVCHS162830AGR	ACTIVE	TSSOP	DBB	80	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
ALVCHS162830AGRE4	ACTIVE	TSSOP	DBB	80	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
ALVCHS162830AGRG4	ACTIVE	TSSOP	DBB	80	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

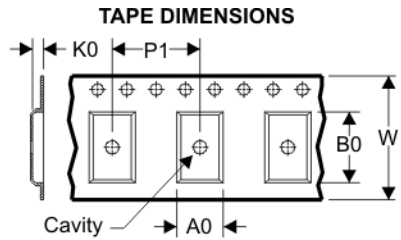
**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

**Important Information and Disclaimer:**The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

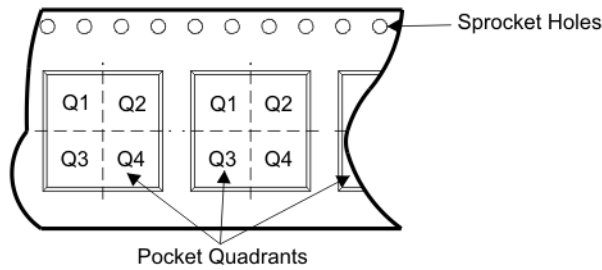
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**TAPE AND REEL BOX INFORMATION**



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**



Device	Package	Pins	Site	Reel Diameter (mm)	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74ALVCHS162830AGR	DBB	80	SITE 41	330	24	8.4	17.3	1.7	12	24	Q1

## TAPE AND REEL BOX DIMENSIONS



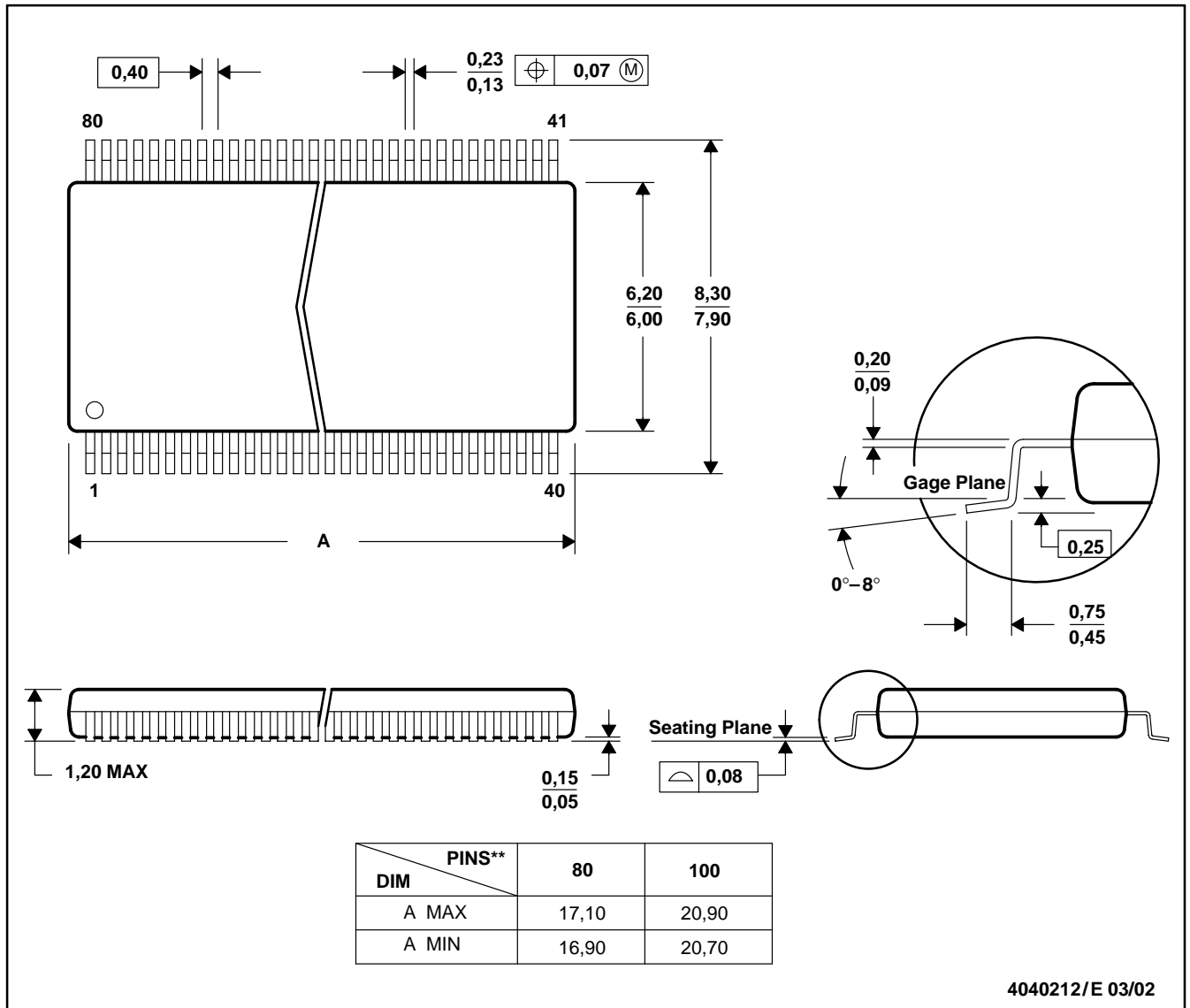
Device	Package	Pins	Site	Length (mm)	Width (mm)	Height (mm)
74ALVCHS162830AGR	DBB	80	SITE 41	346.0	346.0	41.0



DBB (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

80 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Falls within JEDEC : 80 Pin – MO-153 Variation FF  
 100 Pin – MO-194 Variation BB

## IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

<b>Products</b>		<b>Applications</b>	
Amplifiers	<a href="http://amplifier.ti.com">amplifier.ti.com</a>	Audio	<a href="http://www.ti.com/audio">www.ti.com/audio</a>
Data Converters	<a href="http://dataconverter.ti.com">dataconverter.ti.com</a>	Automotive	<a href="http://www.ti.com/automotive">www.ti.com/automotive</a>
DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>	Broadband	<a href="http://www.ti.com/broadband">www.ti.com/broadband</a>
Interface	<a href="http://interface.ti.com">interface.ti.com</a>	Digital Control	<a href="http://www.ti.com/digitalcontrol">www.ti.com/digitalcontrol</a>
Logic	<a href="http://logic.ti.com">logic.ti.com</a>	Military	<a href="http://www.ti.com/military">www.ti.com/military</a>
Power Mgmt	<a href="http://power.ti.com">power.ti.com</a>	Optical Networking	<a href="http://www.ti.com/opticalnetwork">www.ti.com/opticalnetwork</a>
Microcontrollers	<a href="http://microcontroller.ti.com">microcontroller.ti.com</a>	Security	<a href="http://www.ti.com/security">www.ti.com/security</a>
RFID	<a href="http://www.ti-rfid.com">www.ti-rfid.com</a>	Telephony	<a href="http://www.ti.com/telephony">www.ti.com/telephony</a>
Low Power Wireless	<a href="http://www.ti.com/lpw">www.ti.com/lpw</a>	Video & Imaging	<a href="http://www.ti.com/video">www.ti.com/video</a>
		Wireless	<a href="http://www.ti.com/wireless">www.ti.com/wireless</a>

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
Copyright © 2007, Texas Instruments Incorporated